

DLBeam™ High Speed Connectors

Engineered for Enhanced Signal Integrity

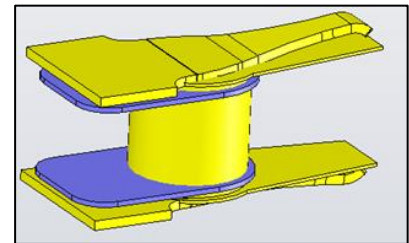
OVERVIEW

Engineered specifically for high speed, the new DLBeam™ construction offers enhanced signal integrity for applications up to 56Gbps. Utilizing a modified design and manufacturing flow, DLBeam™ products take advantage of 60% less surface area to significantly reduce parasitic capacitance. The design also features a shorter, more direct signal path to minimize attenuation.

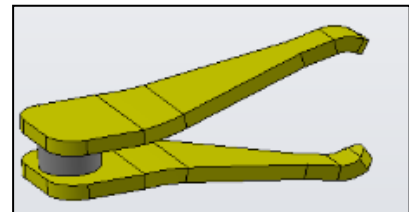
The new DLBeam™ interposer construction can be applied to PCBeam connector products at 1mm pitch and higher, and will scale to finer pitches in the future.

FEATURES

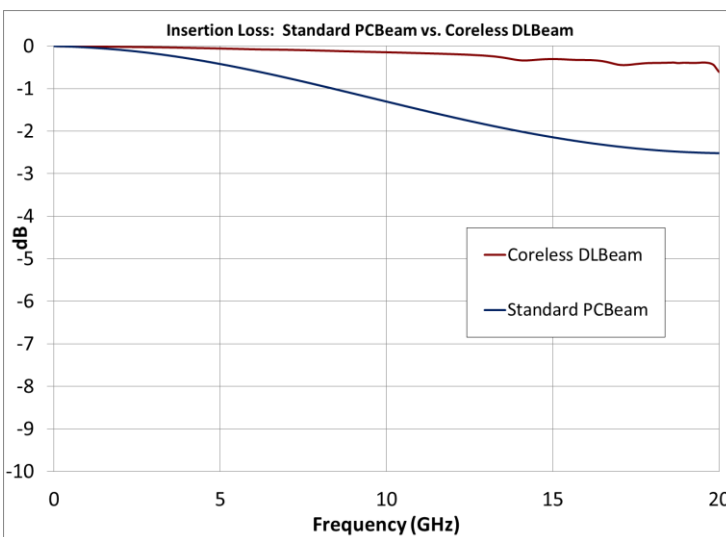
- Now available for PCBeam designs at 1mm at higher
- Up to 70% less insertion loss vs. standard PCBeam at 20GHz
- Ultra-low profile capability as low as 0.28mm (coreless option)
- Thickness up to 4mm
- Current capacity to >2A per single position
- Option for separable (LGA/LGA) or solderable (LGA/BGA) mounting to PCB or FPC
- Mechanically interchangeable with standard PCBeam interposers (no hardware changes needed if migrating to DLBeam)
- Compliant with ROHS 2011/65/EU and IPC-4101B (halogen-free)



PCBeam™ Standard Construction



Coreless DLBeam™ Construction



Ultra-Thin Coreless Construction

FOR MORE INFORMATION

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